

Application No.: 09/928,991

Docket No.: 4459-058

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-16. (cancelled)

17. (currently amended) In combination,

a semiconductor packaging mold having at least one mold cavity for packaging semiconductor packages;

a cleaning substrate for use in cleaning said semiconductor packaging mold, said substrate having at least a first protrusion on the upper surface thereof, said first protrusion being sized and shaped to be completely received within said mold cavity;

wherein the first protrusion conforms in shape with said mold cavity; and

The combination of claim 16, wherein the substrate is made of paper.

18. (previously presented) The combination of claim 17, wherein

the mold comprises at least an upper mold having at least a first recess, and a lower mold having at least a second recess, and the first recess and the second recess define said mold cavity when the upper mold and the lower mold are closed;

the cleaning substrate further comprises at least a second protrusion on the lower surface of the substrate, the first protrusion is completely contained within the first recess of the upper mold and the second protrusion is completely contained within the second recess of the lower mold when the cleaning substrate is placed in the mold and the mold is closed.

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19. (previously presented) The combination of claim 18, wherein the first and second protrusions conform in shape with said first and second recesses, respectively.

20-22. (cancelled)